

U.S. Application No. 10/502,117
Reply to Office Action of October 7, 2008
Amendment dated: February 9, 2009

REMARKS:

Applicant has carefully considered the Examiner's analysis and rejections set forth based upon the admitted prior art and the Kubota reference. In light of the Examiner's analysis, Applicant has cancelled claims 1-20 and substituted a single new method and device claim which clarifies the differences between the admitted prior art and the present invention.

As described in the specification, the present invention is directed to a high-frequency module and a method of manufacturing a high frequency module wherein a first organic insulating layer having no glass fibers formed therein is provided. The first organic insulating substrate has conductive portions formed on the top and bottom surfaces of the first organic substrate. A prepreg layer having no glass fibers formed therein is formed between the first organic having the conductive portions formed thereon and a second organic substrate having conductive portions formed at top and bottom surfaces thereof.

An insulating layer is formed over the conductive portions located at the top surface of the first organic substrate and high frequency circuit components are thereafter formed over the insulating layer. Significantly, there is no conductive portion on either the top or bottom surfaces of the first organic substrate located perpendicularly below high frequency circuit components that are formed over the insulating layer. Advantageously, by forming the high frequency circuit component over portions of the first organic substrate wherein there are no conductive portions are located, improved operating characteristics are achieved. Furthermore, the variations which are the result of the

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presence of the woven glass fibers in the substrate immediately below the high frequency circuit components are avoided.

Applicant respectfully submits that the prior art references fail to either teach or suggest the presently claimed invention as now specified. Applicant specifically notes that the combination of the Kubota reference with the acknowledged prior art will not result in the invention as now specified. Notably, the acknowledged prior art indicates that the glass fibers should be located in regions immediately below the insulating layer upon which the high frequency circuit components are formed. (i.e. the first organic substrate which applicant specifies is free of the glass fibers in the acknowledged prior art). Furthermore, neither Kubota, the acknowledged prior art nor any of the remaining references of record teach or suggest the formation of a prepreg layer between first and second organic substrates upon which conductive portions are located at top and bottom surfaces thereof.

Accordingly, at the very least for the reasons specified herein, Applicants submits that all claims in the application stand in condition for allowance.

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In the event that it is deemed necessary, the Commissioner is hereby authorized to charge any fees due or to credit any overpayment to Deposit Account No. 50-3891.

Date:

2/9/09

Respectfully Submitted,

(Reg. #37,607)

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